

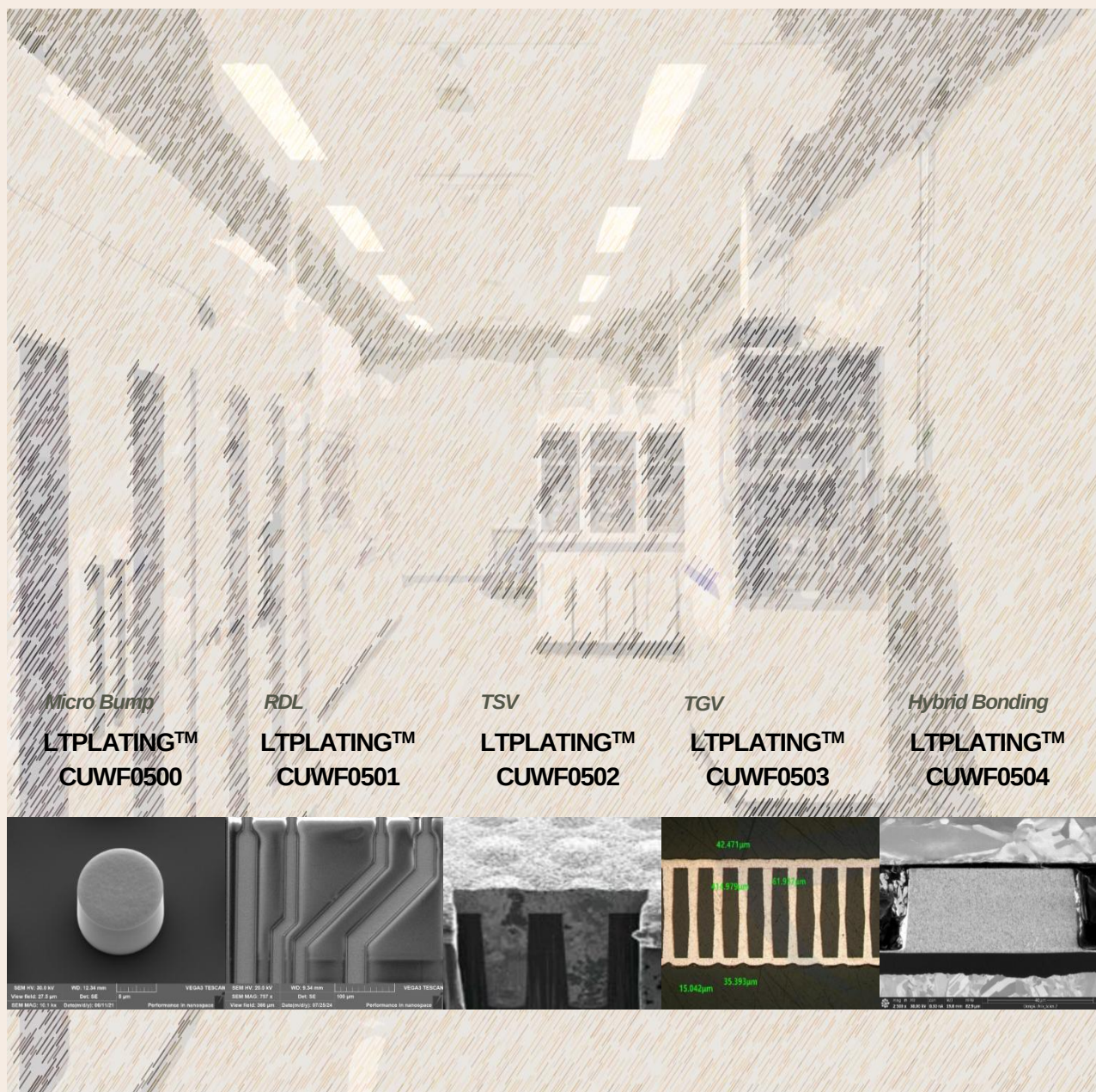
Plating

for Semiconductors



LTPLATING™ Cu plating

A versatile portfolio of Cu plating solutions suitable for various applications and process requirements.



Detailed information available upon request
hypark@ltmetal.co.kr



Recycle Gold UL Certified
Some of our gold products have achieved UL certification

Wafer Process

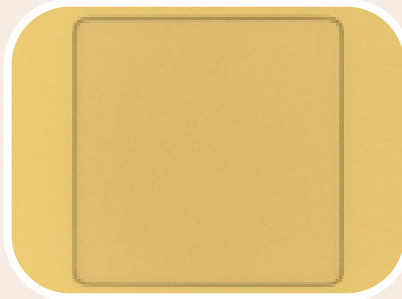
Gold for Bump

Microfab Au 3151
(Non-cyan)



Gold for Strike

Microfab Au FL 2100
(Non-cyan)



Nickel

Microfab Ni200



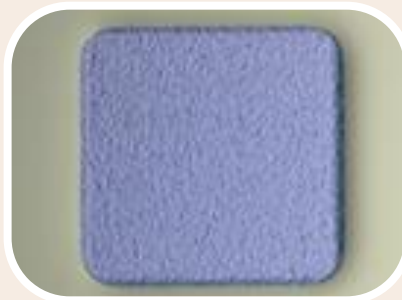
Copper

LTPLATING CUWF 0500



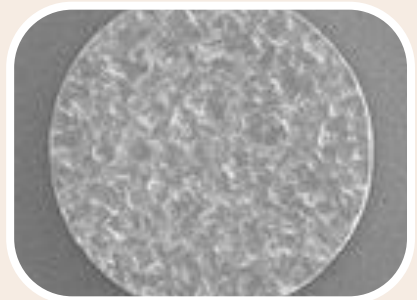
Palladium

Pd0600



Sn-Ag plating

LTPLATING SNAG 10
LTPLATING SNAG 20



R&D Equipment

					
8, 12 in ECD	Profiler	3D Laser Microscope	XRF (X-ray Fluorescence)	Shear Tester	FE-SEM (Field Emission Scanning Electron Microscope)

PLP

Panel Level Package

PCB Process

Advanced Cu-Ni-Au or Sn/Ag Process
for PLP plating process

Acid Cleaner
Galvanomeister15

Soft etching
Galvanomeister74

Copper
LTPLATING™ CUWF0500

Nickel
Galvanomeister Ni400

Gold for strike
GalvanomeisterTN

With PGC
Potassium Gold Cyanide
 $\text{KAu}(\text{CN})_2$

SnAg Plating
LTPLATING SNAG 20

Gold for soft
Galvanomeister GF210

With PGC
Potassium Gold Cyanide
 $\text{KAu}(\text{CN})_2$

Gold for PCBs
Potassium Gold Cyanide
 $\text{KAu}(\text{CN})_2$

Plating Solution for PLP
Pannel Level Package
(Pre-treatment, Nickel, Gold)

R&D Equipment

					
Hardness Analyzer	Ion Milling System	CVS (Cyclic Voltammetric Stripping)	ICP-MS (Inductively Coupled Plasma Mass Spectrometry)	Ion Chromatography	Titrator